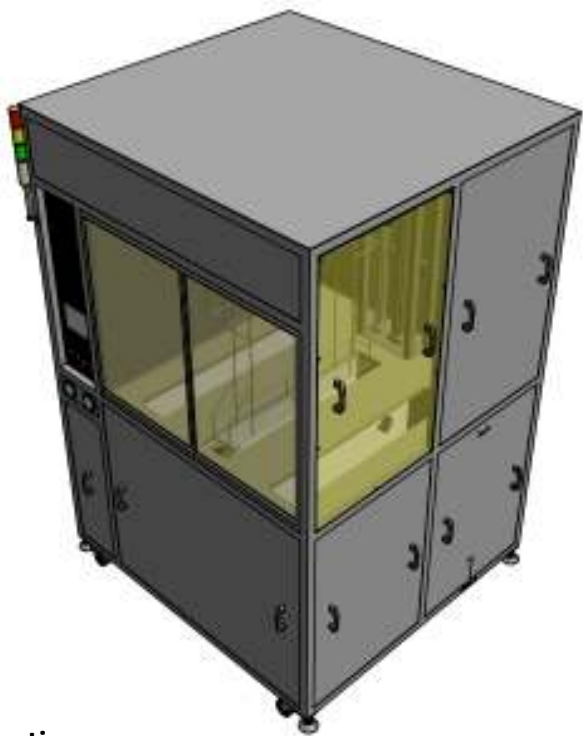


TSC-FA
AQUEOUS / SEMI-AQUEOUS



Function

The TSC-FA series will be loaded from front by open sliding door. STENCIL / MISPRINT PCBA will be run thru 2-STEP or 3-STEP cleaning process automatically by transfer arm mechanism, this machine with flexi-process which capable to handle both lead free and non-lead free solder paste, auto fast-agitating mechanic which suitable for misprint PCBA which no allowed for ultrasonic cleaning application, reciprocating CDA Blow dry mechanism to dry-off the parts effectively.

Programming / Control

TSC-FA series will be controlled by PLC, the cycle time of the respective the parameter setting is freely programmable in PLC with HMI interface for parameter setting.



TECHNICAL SPECIFICATION	TSC-20FA	TSC-30FA
Overall dimension (LxWxH)	1250x1400x2250mm	1500X1400X2250
Max object handle capability	H650~750mm x W750mm	H650~750mm x W750mm
Cycle time	15-20min	15-20min
Wash Tank capacity	150L	150L
Filtration	10 micron	10 micron
Ultrasonic Power / Frequency	1500W / 40kHz	1500W / 40kHz
Power Source	220-240 VAC, 1Ph	380-415 VAC, 3Ph
Framework & cover	Fully stainless steel	Fully stainless steel
Weight	500kg	600kg
CDA Blow Dry	YES	YES
Compress Air	3000 LPM @ 3bar	3000LPM @ 3bar